

TRANSMITTAL

Electronic Version v1.1

Stylesheet Version v1.1.0

Title of Invention	Stacking Memory Chips Using Flat Lead-Frame with Breakaway Insertion Pins and Pin-to-Pin Bridges		
Application Number :			
Date :			
First Named Applicant:	Ren-Kang Chiou		
Confirmation Number:			
Attorney Docket Number:	ML-17		
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Submitted By:		Elec. Sign.	Sign. Capacity
Stuart T Auvinen Registered Number: 36,435		/e/stuauvinen	Agent

Documents being submitted:	Files
us-ids	ML17ex-usidst.xml us-ids.dtd us-ids.xsl
us-request	ML17ex-usrequ.xml us-request.dtd us-request.xsl
us-fee-sheet	ML17ex-usfees.xml us-fee-sheet.xsl us-fee-sheet.dtd
application-body	ML17e-trans.xml us-application-body.xsl application-body.dtd wipo.ent mathml2.dtd mathml2-qname-1.mod isoamsa.ent isoamsb.ent isoamsc.ent isoamsn.ent isoamso.ent isoamsr.ent isogr3.ent isomfrk.ent isomopf.ent isomscr.ent isotech.ent isobox.ent isocyr1.ent isocyr2.ent isodia.ent isolat1.ent isolat2.ent isonum.ent isopub.ent mmlextra.ent mmlalias.ent soextblx.dtd fgML17e01.TIF fgML17e02.TIF fgML17e03.TIF fgML17e04.TIF fgML17e05.TIF fgML17e06.TIF fgML17e07.TIF fgML17e08.TIF fgML17e09.TIF fgML17e10.TIF fgML17e11.TIF fgML17e12.TIF

us-declaration	fgML17e13.TIF OathML17e.tif
Comments	